

Bandpass Filter

SMT

BFCN-ED13661/4

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability.
At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.

Please click "Back", and then click "Contact Us" for Applications support.



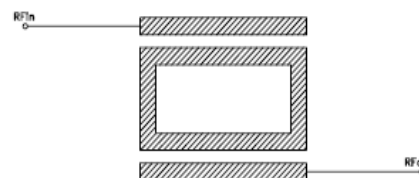
CASE STYLE : FV1206-4

ELECTRICAL SPECIFICATIONS 50Ω @ +25°C							
Parameters		F#	Frequency (MHz)	Min.	Typ.	Max.	Units
Pass Band	Center Frequency				7200		MHz
	Insertion Loss	F1-F2	7100-7300		2.0	3.5	dB
	VSWR	F1-F2	7100-7300		1.4		:1
Stop Band, Lower	Insertion Loss	DC-F5	DC-6500	12	15		dB
		F5-F3	6500-6650		15		dB
	VSWR	DC-F3	DC-6650		30		:1
Stop Band, Upper	Insertion Loss	F4-F6	8150-8500		12		dB
		F6-F7	8500-14000	15	20		dB
	VSWR	F4-F7	8150-14000		30		:1

MAXIMUM RATINGS	
Operating Temperature	-55°C to 100°C
Storage Temperature	-55°C to 100°C
RF Power Input*	2W max. @ 25°C

*Passband rating, derate linearly to 0.5W at 100°C ambient

PIN CONNECTIONS	
RF IN	1
RF OUT	3
GROUND	2,4

Functional Schematic

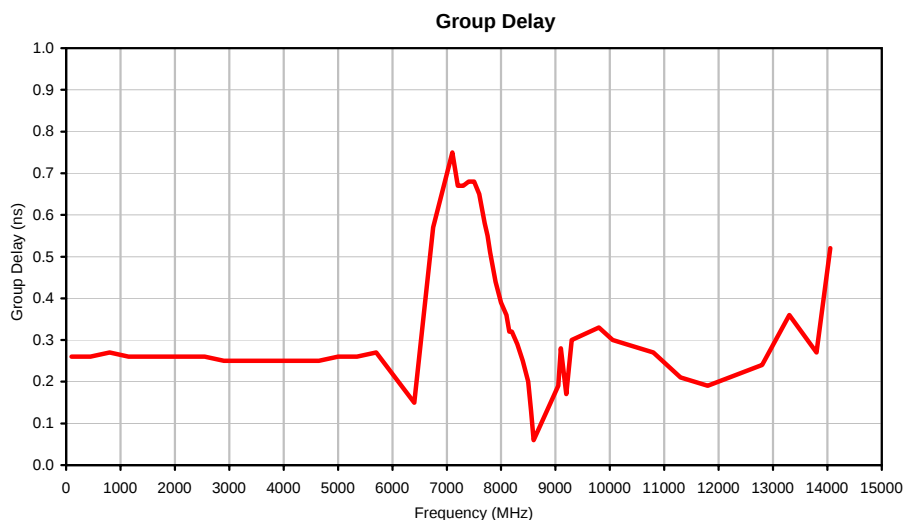
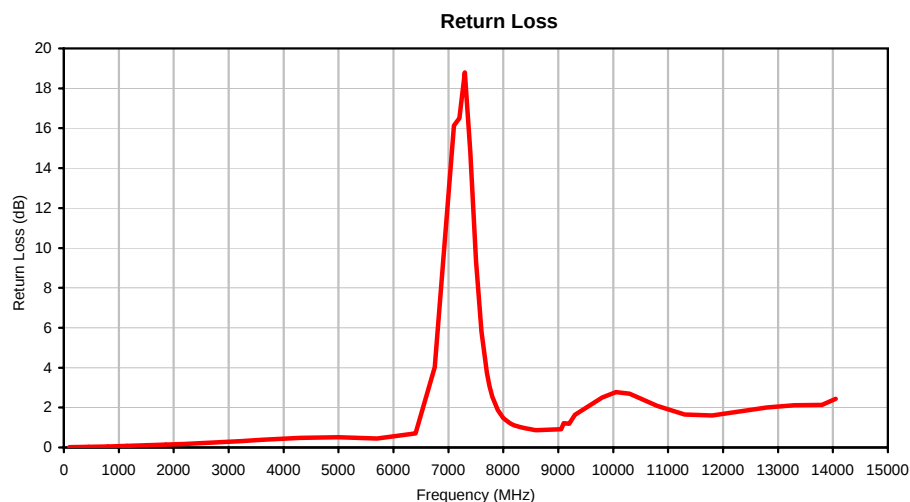
Ceramic Bandpass Filter

BFCN-ED13661/4

Typical Performance Data

FREQUENCY	INSERTION LOSS	RETURN LOSS	GROUP DELAY
(MHz)	(dB)	(dB)	(ns)
100.0	44.36	0.01	0.26
450.0	31.36	0.03	0.26
800.0	26.49	0.05	0.27
1150.0	23.55	0.08	0.26
1500.0	21.53	0.11	0.26
1850.0	20.05	0.14	0.26
2200.0	18.94	0.18	0.26
2550.0	18.08	0.22	0.26
2900.0	17.41	0.27	0.25
3250.0	16.84	0.32	0.25
3600.0	16.36	0.38	0.25
3950.0	15.92	0.44	0.25
4300.0	15.51	0.48	0.25
4650.0	15.13	0.50	0.25
5000.0	14.82	0.51	0.26
5350.0	14.66	0.48	0.26
5700.0	14.75	0.45	0.27
6400.0	21.17	0.70	0.15
6750.0	8.29	4.03	0.57
7100.0	1.91	16.13	0.75
7200.0	1.77	16.50	0.67
7300.0	1.74	18.79	0.67
7400.0	1.95	14.84	0.68
7500.0	2.55	9.34	0.68
7600.0	3.67	5.81	0.65
7700.0	5.24	3.74	0.58
7750.0	6.14	3.08	0.55
7800.0	7.14	2.53	0.51
7900.0	9.18	1.87	0.44
8000.0	11.32	1.47	0.39
8100.0	13.52	1.25	0.36
8150.0	14.66	1.17	0.32
8200.0	15.82	1.11	0.32
8300.0	18.25	1.02	0.29
8400.0	20.94	0.97	0.25
8500.0	24.02	0.91	0.20
8550.0	25.84	0.88	0.13
8600.0	27.87	0.86	0.06
9050.0	28.04	0.92	0.19
9100.0	26.83	1.22	0.28
9200.0	24.81	1.18	0.17
9300.0	23.42	1.63	0.30
9800.0	20.08	2.50	0.33
10050.0	20.06	2.78	0.30
10300.0	20.37	2.70	0.29
10800.0	22.03	2.09	0.27
11300.0	24.69	1.65	0.21
11800.0	27.82	1.60	0.19
12800.0	26.19	2.00	0.24
13300.0	24.29	2.11	0.36
13800.0	24.16	2.14	0.27
14050.0	19.54	2.44	0.52

Typical Performance Curves



Sheet 4 of 8

DEVICE ORIENTATION IN T&R

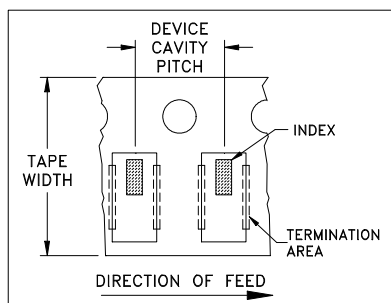


ILLUSTRATION 1



ILLUSTRATION 2



ILLUSTRATION 3

Applicable Case Styles

FV1206-1
FV1206-3

Applicable Case Styles

FV1206-4
FV1206-5
FV1206-6
FV1206-7
FV1206-9

Applicable Case Styles

FV1206-11
FV1206-12
GE0805C-18
NL1008C-6
NL1008C-7
NL1008C-9
NL1008C-10
NL1008C-12

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel	
8	4	7	Small quantity standards (see note)	20
				50
				100
				200
				500
				1000
			Standard	3000

Note: Please consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

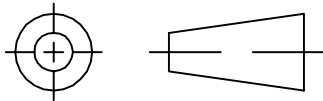


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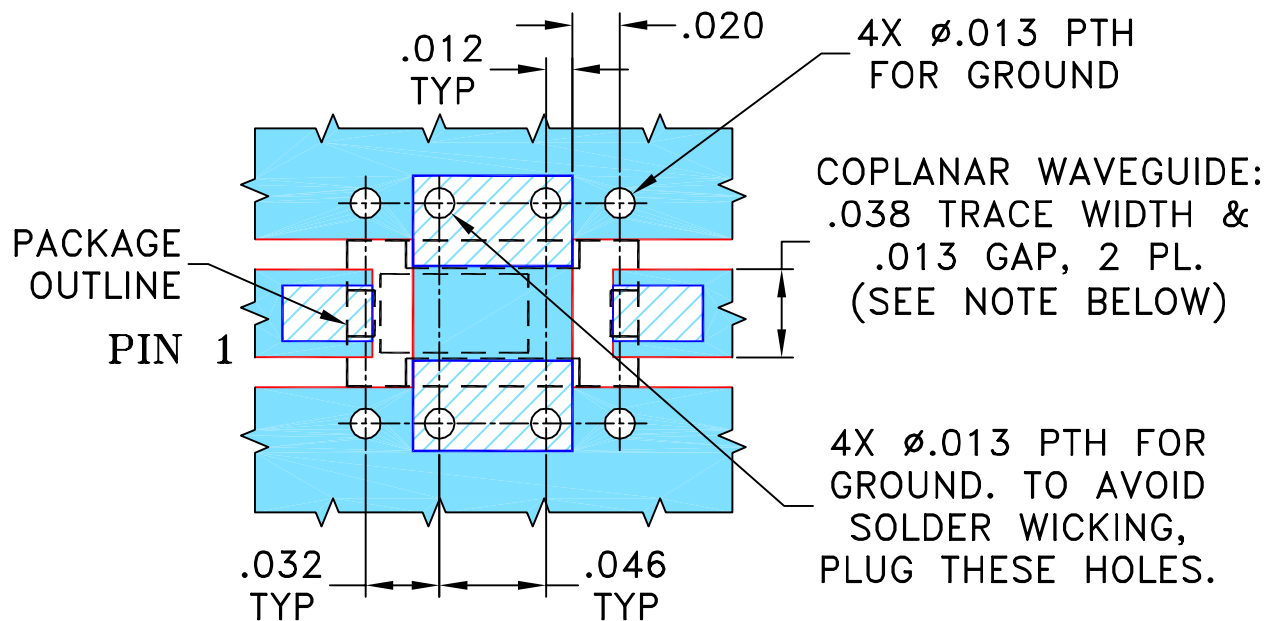
THIRD ANGLE PROJECTION



REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M123589	NEW RELEASE	01/15/09	AV	ABD

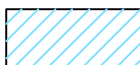
**SUGGESTED MOUNTING CONFIGURATION
FOR FV1206-4 CASE STYLE, "04FL01" PIN CODE**



- NOTE:** 1. TRACE WIDTH IS SHOWN FOR ROGERS R04350B WITH DIELECTRIC THICKNESS .020" ± .0015". COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED

INITIALS

DATE

DIMENSIONS ARE IN INCHES

TOLERANCES ON:

2 PL DECIMALS ±

3 PL DECIMALS ± .005

ANGLES ±

FRACTIONS ±

DRAWN

AV

07/10/09

CHECKED

IL

01/15/09

APPROVED

ABD

01/15/09

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ASHEETA1.DWG REV:A DATE:01/12/95



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PL, 04FL01, FV1206-4, BFCN, TB-518+

SIZE
ACODE IDENT
15542

DRAWING NO:

98-PL-305

REV:

OR

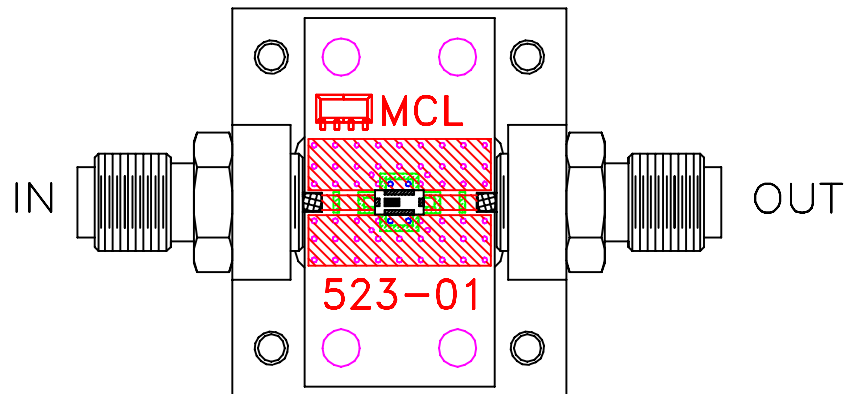
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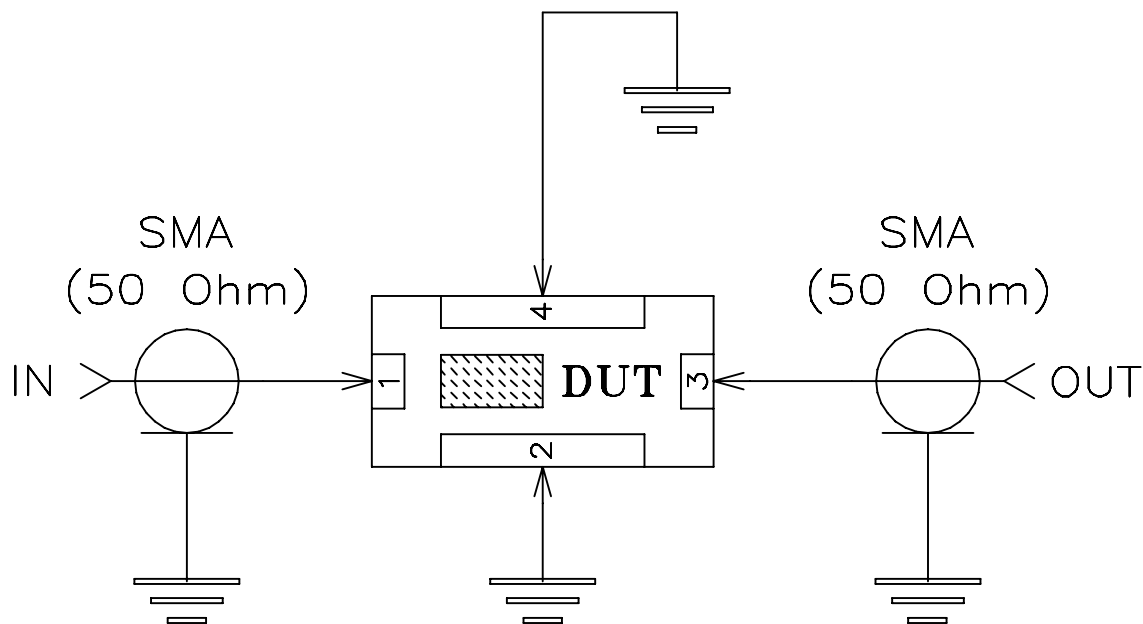
SHEET:

1 OF 1

Evaluation Board and Circuit



TB-518+



Schematic Diagram

Notes:

1. 50 Ohm SMA Female connectors.
2. PCB Material: R04350 or equivalent,
Dielectric Constant=3.5, Thickness=.020 inch.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 100°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A